

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

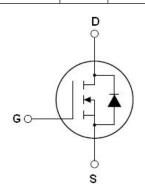
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V _{DS min@Tjmax}	650	V
R _{DS(ON)TYP}	180	mΩ
ID	18	Α
Qg	22.8	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking
NCE60NF200K	TO-252	NCE60NF200K



TO-252

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	600	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	V _G s	±30	V
Gate-Source Voltage (VDS=0V) DC	V _G s	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	18	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	12.6	Α
Pulsed drain current (Note 1)	I _{DM} (pluse)	54	Α
Maximum Power Dissipation(Tc=25°C)	P _D	150	W
Derate above 25°C		1.0	w/°C
Avalanche current ^(Note 1)	I _{AS}	3.5	Α
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+175	°C

^{*} limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.0	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	'			•	•	
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	600			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			300	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3.5	4.2	5.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =9A		180	200	mΩ
Dynamic Characteristics						
Input Capacitance	C _{lss}	.,		1157		pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V,		60		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		1.5		pF
Total Gate Charge	Qg			22.8		nC
Gate-Source Charge	Qgs	V _{DS} =400V,I _D =9A,		9.1		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		6		nC
Gate plateau voltage	Vgp			6.5		V
Intrinsic gate resistance	R _G	f = 1 MHz open drain		20		Ω
Switching times	•					
Turn-on Delay Time	t _{d(on)}			25		nS
Turn-on Rise Time	t _r	$V_{DD}=380V, I_{D}=9A,$		16		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=1.7\Omega, V_{GS}=10V$		75		nS
Turn-Off Fall Time	t _f			9		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T 0500			18	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			54	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =18A,V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}	T: 05°C 04		90		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =9A,		0.32		uC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/μs		7		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}$ C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

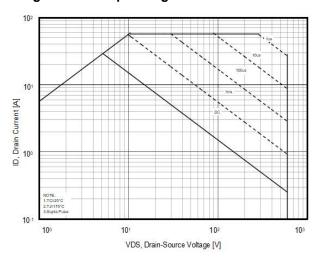


Figure 3. Transfer characteristics

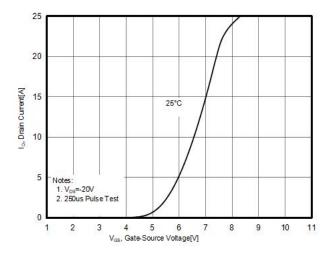


Figure 5. RDS(ON) vs Junction Temperature

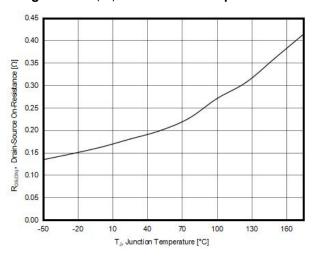


Figure 2. Capacitance

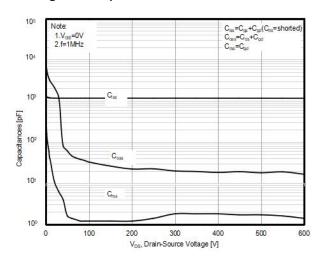


Figure4. Output characteristics

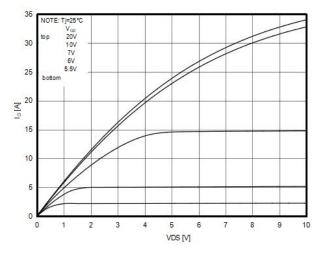


Figure 6. BV_{DSS} vs Junction Temperature

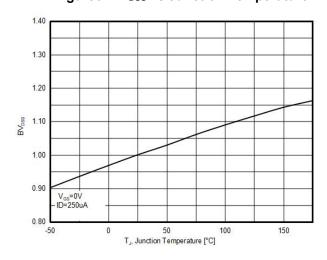




Figure 7. Maximum I_D vs Junction Temperature

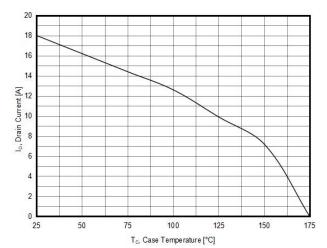


Figure8. Gate charge waveforms

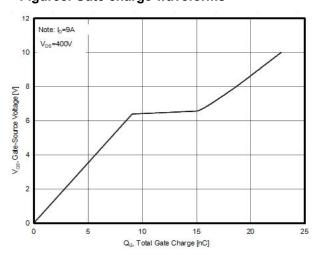


Figure 9. Static drain-source on resistance

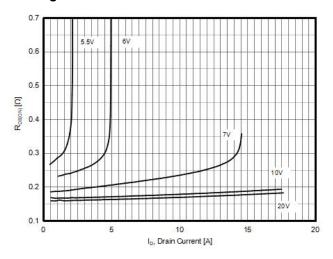
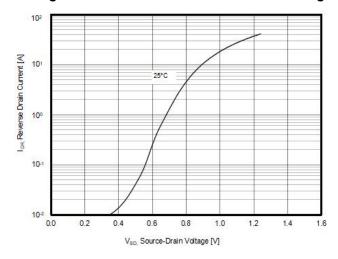


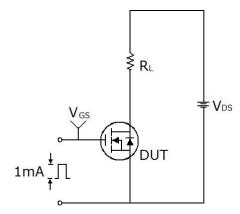
Figure 10. Source-Drain Diode Forward Voltage

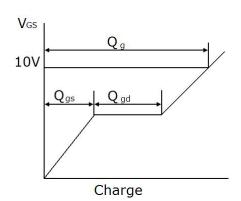




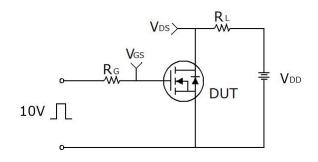
Test circuit

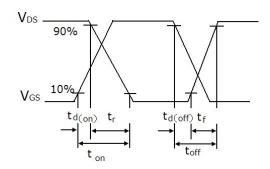
1) Gate charge test circuit & Waveform



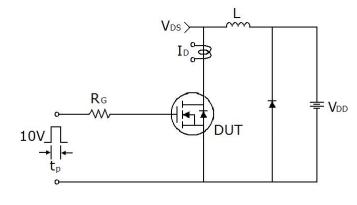


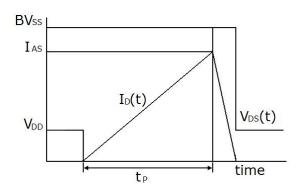
2) Switch Time Test Circuit:





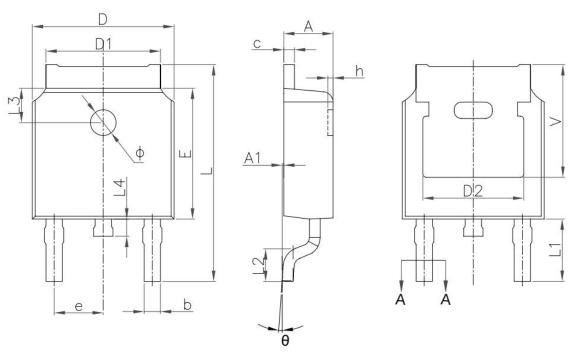
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-252-E Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches	
	Min.	Max.	Min.	Max.	
А	2.20	2.40	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
b	0.66	0.86	0.026	0.033	
b1	0.73	0.79	0.029	0.031	
С	0.46	0.58	0.018	0.023	
c1	0.50	0.52	0.020	0.020	
D	6.50	6.70	0.256	0.264	
D1	5.10	5.46	0.201	0.215	
D2	4.83	3 REF	0.19REF		
Е	6.00	6.20	0.236	0.244	
е	2.19	2.39	0.086	0.094	
L	9.80	10.40	0.386	0.409	
L1	2.90	2.90 REF		REF	
L2	1.40	1.70	0.055		
L3	1.60	1.60 REF		REF	
L4	0.60	1.00	0.024	0.039	
Ф	1.10	1.30	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.00	0.30	0.000	0.012	



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